KIEN SEONG, KAN

LED, CAMERA & LIDAR ENGINEER

Taiwan Employment Gold Card Holder : **A800498425** .

I'm an experienced LED, camera & lidar process & test engineer, currently based in Malaysia. I love everything that has to do with mobile market, camera technology, & self-driving development. I enjoy participating in Industrial / Mechanical design, manufacturing and bring final product in volume to consumer space.

Phone : +60 16 470 8917 **Email** : kskan2005@hotmail.com **LinkedIn** : linkedin.com/in/kskan
Webpage : http://kan-family.in/   **Line ID :** kskan2915
Citizen : Malaysian, born in 1980.

EDUCATION

➤ 2001 - 2004
Bachelor's degree in computer science
(First Class Honor)
University Putra Malaysia
Study of computational & networking engineering. Include on C++ & VB programming, design network architecture in Wan / MAN / LAN .

LANGUAGE KNOWN

➤ WRITTEN

English	████████
Chinese	██████
Malay	████▒

➤ SPOKEN

English	████████
Chinese	██████
Malay	████▒

SKILLS

➤ SOFTWARE

JMP	████████▒
Minitab	███████▒
Microsoft Office	████████▒
Mac Keynote, Number	███████▒
Google Sheet	████████▒
Python	███████▒
Microsoft VB VC#	██████▒

➤ PROFESSIONAL

- ⊘ Program Management
- ⊘ Shop Floor Management
- ⊘ Supplier Management
- ⊘ Product Failure Analysis
- ⊘ Process Improvement
- ⊘ Equipment Optimization

- ⊘ Module Process Development
  SMT
  FOL: Die Attach, Wire bond …
  MOL: Active Alignment …
  EOL: ACF, Sealing, Flex Bend …
  Test : Camera Test, LED Test …

WORK EXPERIENCES

2024 (Feb – Jul)
Attach Point Intelligent Equipment (HQ: Dongguan)
Consultant
- Provide consultation on improving company culture / facility / organization / equipment capability to be competitive in international market.
- Responsible on
  o Lead an engineering team (ME, SW, Process, PM), 15 ppl to develop high accuracy PnP equipment (roadmap: direct bond, flip chip, SiC, TCB, Hybrid Bond).
  o Organization and operational strategic planning (Cleanroom, FA lab, REL lab, organization re-structure), towards an international standard company.

2022 - 2023
Argo AI (HQ: Pittsburgh, Base: Malaysia)
Automotive Lidar Staff Process Engineer (ICT6)
- Work on Level-4 ADAS lidar product
- Manage Lidar assembly supplier – LGIT in Paju & Magok, Korea
- Responsible on
  o Supplier engineering team & NPI line bring up, MP ramping.
  o Participate and drive on lidar process development, especially on critical optomechanical process like FACS AA / VBG AA / Laser-FPA Alignment.
  o Aggressively involve in every aspect of the product, including engineering, manufacturing, equipment selection & buyoff, failure analysis & reliability with best-in-class specification.
  o Within internal team, frequently communicate and collaborate with cross functional team in design review, issue discussion, schedule planning & other like technology & cost saving brainstorming.
  o With supplier team, micromanage production line readiness, process development progress (DOE …), FACA & yield bridge, also helping on direct & indirect material tracking , reliability & test issue discussion.

2018 – 2022 & 2013 - 2016
Apple Computer (HQ: Cupertino, Base: Singapore)
Mobile Camera / Depth Module Staff Process Development Engineer (ICT5)
- Work on camera/depth module in Apple iPhone & iPad product.
- Qualify and manage module assembly supplier:
    - LGIT in Gumi, Korea
    - STATS ChipPac in Incheon, Korea
    - Sharp in Ho Chih Min, Vietnam
    - Sony in Kumamoto, Japan
    - DPBU in Shenzhen, China
- Responsible on
    - Supplier engineering team NPI line bring up, MP ramping.
    - Participate and drive on module process development, cover:
        - FOL – SMT, DA, WB, GA, HA, Active Alignment
        - EOL –Soldering, ACF, Stiffener Attach, Flex Bending, Side Sealing
        - Test – SFR, RI, RU, CU, Actuator Characterization, OIS Characterization
    - Aggressively involve in every aspect of the product, including engineering, manufacturing, equipment selection & buyoff, failure analysis & reliability with best-in-class specification.
    - Within internal team, daily communicate and collaborate with cross functional team in design review, issue discussion, schedule planning & others.
    - With supplier team, micromanage production line readiness, process development progress (DOE …), FACA & yield bridge, also helping on direct & indirect material tracking , reliability & test issue discussion.
    - Prepare & review documentation in place:
        - Engineering requirement specification [Internal]
        - Design documents-2D/3D Drawing, EE schematic
        - Process documentation-MBO, FMEA, CP, SOP, MSOP, Tray design, UPH sheet, OEE [Supplier]
        - Weekly engineering sync slides. [Internal + Supplier]
        - Management team / customer visit slides. [Internal]

2016 - 2017
Amazon Lab126 (HQ: Sunnyvale, Base: Shanghai)
Camera Product Senior Test Engineer
- Work on Echo Look project, co-develop on the LED Flash Calibration system, RGB camera testing, Intel IR camera re-calibration, RGB to IR Camera Mapping Calibration & validation.
- Manage supplier like Compal, Foxconn, Chicony, Sunny, involving in yield improvement, test time & sequence optimization.

2011 - 2012
Digital Optics Corporation (HQ: San Jose, Base: Taiwan)
MEMS Actuator Test Manager

2007 - 2010
Flextronics Vista Point (Base: Malaysia)
Senior Manufacturing Test Engineer

2004 - 2007
Philips Lumileds (Base: Malaysia)
NPI Junior Test Engineer
Work on Luxeon Level 1 LED package test & sort system development. Involve in software programming like test binning characterization, cover LED brightness, forward voltage & color wavelength, also integrate hardware like light collector sphere/cone, Keithley 2400 family SMU, GPIB & serial port, IS spectrometer.

2010 - 2011
Soraa (Base: Malaysia)
Product Process & Test Engineer
Work on high brightness LED package , co-develop with supplier on substrate coating, sawing, ring dispensing & tester development.